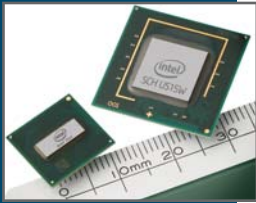


# Advanced Packaging Update: Market and Technology Trends

Vol. 3, 2009



The third volume of the Advanced Packaging Update for 2009 provides an updated economic outlook and examines the general macroeconomic trends in the world economy and the microeconomic trends in the semiconductor packaging and assembly industry. This issue features the results of a survey on lidless packages. An analysis of the developments in fan-out WLPs is provided. Demand and capacity projections for fan-out packages are included. Issues associated with scaling fan-out packages to large panel format are discussed. New package and test developments are discussed.

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